

become small. Thus, to prevent an aluminum conductor from being broken due to migration and to prevent hillock from occurring due to the migration, there has been generally used a method of adding copper of about 0.5% in aluminum used for the aluminum conductor. However, the spacing of metal conductor portions as well as the metal conductor width tends to also become small. Thus, if any precipitate containing copper exists between two metal conductor portions, it becomes the cause of short fault. To address this problem, it is proposed, in JP-A-8-186175, to adopt a method comprising the steps of forming aluminum film at a high temperature so that copper may be dissolved in aluminum, and quenching the aluminum film so that the copper may be prevented from being precipitated during the cooling thereof.

Page 2, paragraph beginning at line 11, has been rewritten as indicated below:

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The precipitation of copper regarding the aluminum conductor is found to proceed due to the diffusion of copper atoms existing in crystal grain boundaries and in crystal grains. Thus, in order to prevent the precipitation from occurring, it is necessary to suppress the diffusion of the copper atoms existing in the aluminum conductor. After performing intensive research for obtaining means for suppressing the diffusion of the copper atoms, the inventors of the invention have discovered that, by adding in the